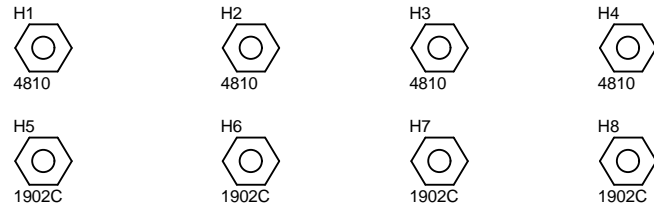


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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 04/01/2017
TID #: TIDA-0130	Project Title: UCC28070 RESISTIVE SENSING	
Number: TIDA-0130	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: TIDA-0130_A.SchDoc	Size: B
Engineer: JOHN GRIFFIN	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





PCB Number: TIDA-0130  
PCB Rev: A

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

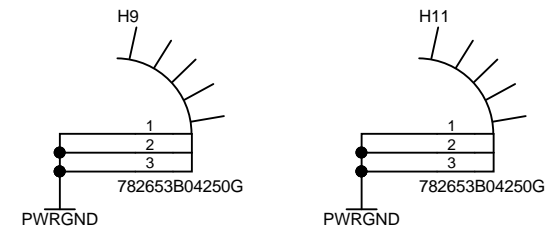
PCB LOGO  
FCC disclaimer

<sup>A</sup>You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.



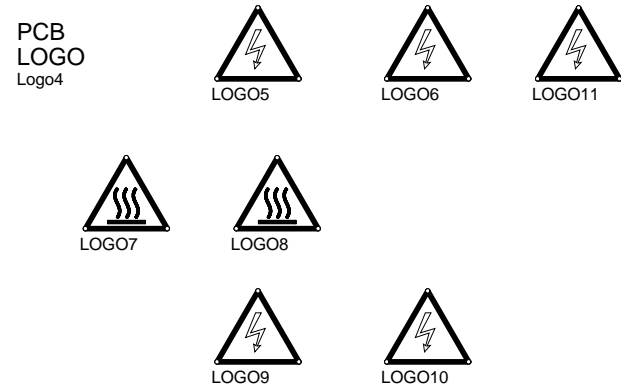
Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



SIL8  
MECH  
SP900S-0.009-00-114

ZZ8  
Assembly Note  
Sil Pad SIL8 to be used between BRIDGE (D2) and HEATSINK (H10)

SIL7  
MECH  
Q3-0.005-00-58

ZZ7  
Assembly Note  
Sil Pads SIL1 through SIL7 o be used between Q1, D3, Q2, D7 and heat sinks

ZZ10  
Assembly Note  
Assemble TO-220S with clips and SIL Pads

H29  
MECH  
MAX01NG

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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 04/01/2017
TID #: TIDA-0130	Project Title: UCC28070 RESISTIVE SENSING	
Number: TIDA-0130	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: TIDA-0130_A-HW.SchDoc	Size: B
Engineer: JOHN GRIFFIN	Contact: http://www.ti.com/support	